## EV-VN7007AH



### VN7007AH Evaluation Board

**Data brief** 



#### **Features**

Max transient supply voltage	V <sub>CC</sub>	40 V
Operating voltage range	V <sub>CC</sub>	4 to 28 V
Typ. on-state resistance (per Ch)	R <sub>ON</sub>	7 mΩ
Current limitation (typ)	I <sub>LIMH</sub>	100 A
Stand-by current (max)	I <sub>STBY</sub>	0.5 μΑ

- Simple single IC application board dedicated for VN7007AH
- Provides electrical connectivity and thermal heat-sinking for easy prototyping
- General device features
  - Single channel smart high-side driver with CurrentSense analog feedback
  - Very low standby current

- Compatible with 3 V and 5 V CMOS outputs
- Diagnostic functions
  - Dedicated high precision proportional load current sense
  - Overload and short to ground (power limitation) indication
  - Thermal shutdown indication
  - OFF-state open-load detection
  - Output short to VCC detection
  - Sense enable/ disable
- Protections
  - Undervoltage shutdown
  - Overvoltage clamp
  - Load current limitation
  - Self limiting of fast thermal transients
  - Loss of ground and loss of VCC
  - Reverse battery
  - Electrostatic discharge protection

## **Applications**

Specially intended for Automotive Smart Power Distribution, Glow Plug, Heating Systems, DC Motors, Relay replacement and high power resistive and inductive actuators.

## **Description**

This board provides you an easy way to connect STMicroelectronics<sup>®</sup> VIPower<sup>®</sup> M0-7 technology into your existing system.

**Table 1. Device summary** 

Order Code	Reference
EV-VN7007AH	VN7007AH Evaluation Board

Overview EV-VN7007AH

#### 1 Overview

The board comes pre-assembled with VN7007AH high-side driver. On board minimum set of electrical components (as for device datasheet recommendation) is enabling the user to directly connect the load, the power supply and the microcontroller without any additional effort in external component design and connection.

The VN7007AH is a single channel high-side driver manufactured using ST proprietary VIPower® technology and housed in the Octapak package. The device is designed to drive 12 V automotive grounded loads through a 3 V and 5 V CMOS-compatible interface, providing protection and diagnostics.

The device integrates advanced protective functions such as load current limitation, overload active management by power limitation and overtemperature shutdown.

A sense enable pin allows OFF-state diagnosis to be disabled during the module low-power mode as well as external sense resistor sharing among similar devices.

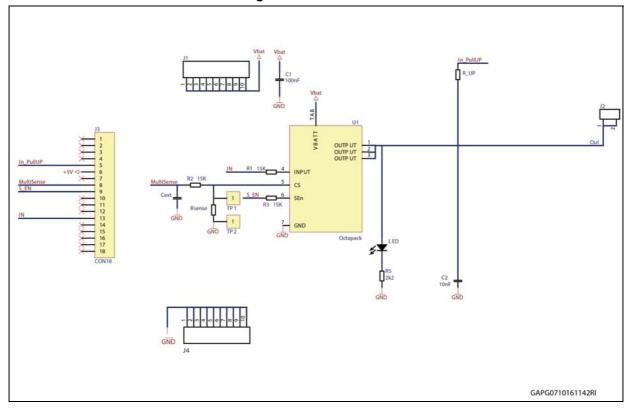


Figure 1. EV-VN7007AH schematic

EV-VN7007AH Board connections

## 2 Board connections

*Figure 2* shows the placement of the connectors to be used for supplying the evaluation board, connecting the load and controlling the functionality and diagnostic of the device.

OUT0 – First power output

OUT1 – Second power output

(not connected for single channel)

OUT1 – Connection to battery (12V)

J3 – Control and diagnostic (see below table)

TP1-TP2 – Connector for plugging sense resistor

GND – Connection to ground

Figure 2. Evaluation board connections

Table 2. J3 connector: pin functions

Connector	Pin number	Pin name	Pin function
J3	14	N/A	Not connected
J3	5	IN_PullUP	Connection to optional external pull-up resistor for open load detection in off-state.
J3	6	+5V	5V Power Supply
J3	7	N/A	Not connected
J3	8	MultiSense	Analog current sense output pin delivers a current proportional to the load current.
J3	9	S_EN	Active high compatible with 3 V and 5 V CMOS outputs pin; it enables the CurrentSense diagnostic pin.
J3	1011	N/A	Not connected
J3	12	N/A	Not connected
J3	13	IN0	Voltage controlled input pin with hysteresis, compatible with 3 V and 5 V CMOS outputs. It controls OUT0 switch state.
J3	14	IN1	Voltage controlled input pin with hysteresis, compatible with 3 V and 5 V CMOS outputs. It controls OUT1 switch state (Input not available for single channel)
J3	1518	N/A	Not connected

**Board connections** EV-VN7007AH

> In case the user wishes to utilize the Current Sense / MultiSense function of the device, it is necessary to plug a sense resistor in Rsense.

The package includes a through-hole resistor, to be mounted on TP1-TP2 - see Figure 4.

Different Rsense values can be adopted based on user preference.

Another option is soldering an SMD resistor on the dedicated PCB pad, as shown in Figure 5.

Figure 3. No sense resistor

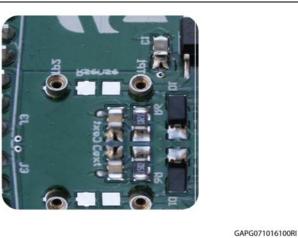
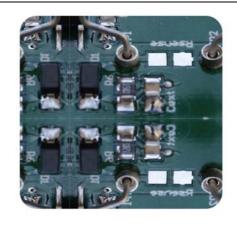


Figure 4. Mounting through-hole sense resistor



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EV-VN7007AH Board connections

Figure 5. Pads for soldering SMD resistor



Thermal data EV-VN7007AH

## 3 Thermal data

Table 3. EV-VN7007AH thermal data

Symbol	Parameter	Max	Unit
Rthj-amb	Thermal resistance junction-ambient (MAX)	39°	°C/W

**Table 4. PCB specifications** 

Parameter	Value
Board dimensions	25 mm x 41.5 mm
Number of Cu layer	2
Layer Cu thickness	35 μm
Board finish thickness	1.6 mm +/- 10%
Board Material	FR4
Thermal vias separation	1.1 mm
Thermal vias diameter	0.5 mm

EV-VN7007AH Revision history

# 4 Revision history

Table 5. Document revision history

Date	Revision	Changes
10-Oct-2016	1	Initial release.

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